TSG-RAN Working Group 1 meeting #16 *TSGR1(00)1288*

Pusan, Korea, October 10-13, 2000

Agenda Item: AH21
Source: CWTS
To: TSG RAN WG1
Title: Modulation and combination of physical channels in the 1.28 Mcps TDD
Document for: Decision

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1. Summary

The section 7.6 has been copied from 3.84 Mcps TDD (version 3.4.0 including the Gain factors) and slightly modified since in the downlink there is no combination of the synchronisation channel and other physical channels, like in 3.84Mcps TDD.

2. Proposal

We propose to modify the following paragraphs in the working CR for the TS25.223 as the description of the modulation for the 1.28Mcps TDD.

---------- Changes to working CR of 25.223 begin ----------

7.6 Modulation for the 1.28 Mcps TDD

The complex-valued chip sequence is modulated as shown in figure [X3].

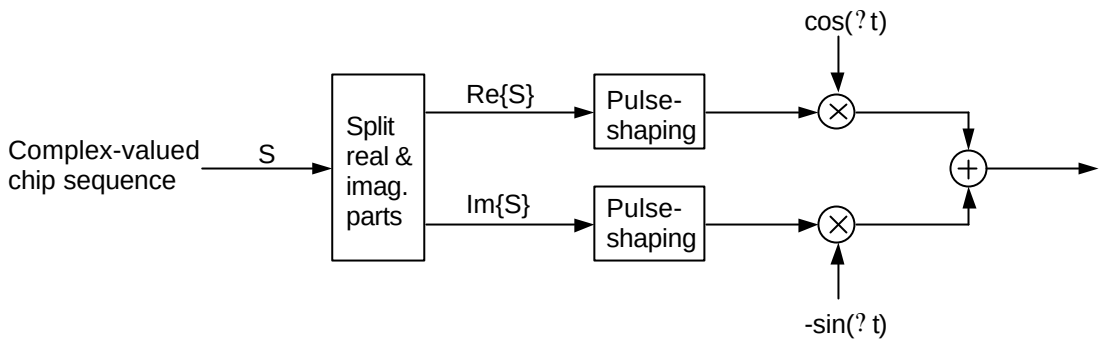

Figure [X3]: Modulation of complex valued chip sequences

The pulse-shaping characteristics are described in [9] and [10].

7.6.1 Combination of physical channels in uplink

The combination of physical channels in uplink is the same as in the 3.84 Mcps TDD cf. [6.5.1 Combination of physical channels in uplink]

7.6.2 Combination of physical channels in downlink

Figure X4 illustrates how different physical downlink channels are combined within one timeslot. Each spread channel is separately weighted by a weight factor G_i.. All downlink physical channels are then combined using complex addition.

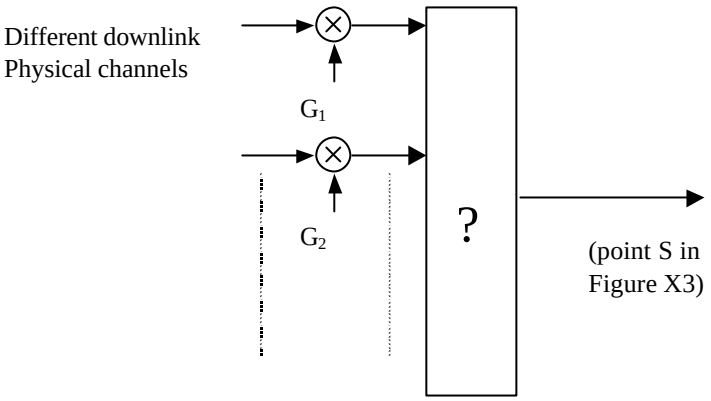

Figure X4: Combination of different physical channels in downlink

---------- Changes to working CR of 25.223 end ----------